

FLUX AND SOLDER PASTE

[ABSTRACT]

A flux containing an organic acid, a water-soluble base agent, and a solvent, but not containing water is adopted. In this flux, the organic acid includes 1,2,3-
5 propanetricarboxylic acid. The water-soluble base agent is one or more selected from the group consisting of a nonionic surfactant and a weak cationic surfactant. The content of the 1,2,3-propanetricarboxylic acid is 1% by mass or more and 15% by mass or less with respect to the total amount of the entire flux, the total content of the water-soluble base agent is 30% by mass or more and 65% by mass or less with respect to the
10 total amount of the entire flux, and the total content of the solvent is 30% by mass or more and 65% by mass or less with respect to the total amount of the entire flux.

According to this flux, the wettability of solder can be enhanced and ball missing after reflow and flux residue washing is suppressed.

[No suitable drawing]